

Amendments to the Specification

Please amend the title as follows:

~~Plasma Etching Process and Chemical Vapor Deposition Process of Depositing a Material~~
~~Over a Semiconductor Substrate~~ Method of Forming a Conductive Contact

At page 1, prior to the Technical Field, please add the following new paragraph:

RELATED PATENT DATA

This patent resulted from a divisional application of U.S. Patent Application Serial No.: 10/013,615, filed October 19, 2001, which resulted from a divisional application of U.S. Patent Application Serial No. 09/360,292, filed July 22, 1999, entitled "Plasma Etching Process" (as amended), naming Sujit Sharan, Gurtej S. Sandhu and Guy T. Blalock as inventors, the disclosure of which is incorporated by reference

Please delete the original abstract.